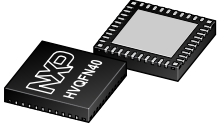


SOT2231-1

H-PQFN40, thermal enhanced - plastic quad flat non-lead, 40 terminals, 0.4 mm pitch, 5 mm x 5 mm x 0.9 mm body

8 May 2026

Package information



1 Package summary

Terminal position code	Q (quad)
Package type descriptive code	H-PQFN40
Package style descriptive code	H-PQFN (thermal enhanced - plastic quad flat non-lead)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	05-05-2026
Manufacturer package code	98ASA02134D

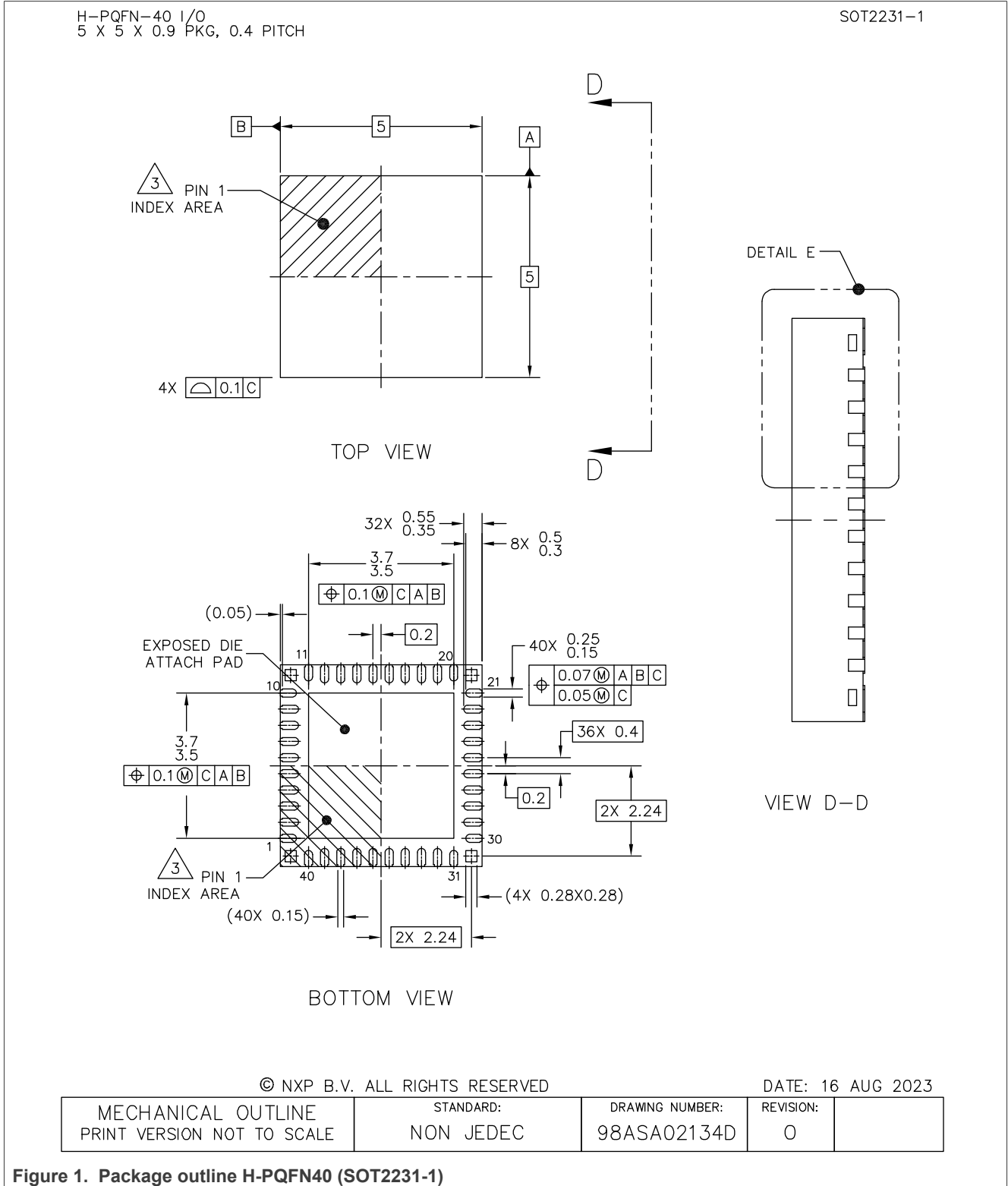
Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	4.9	5	5.1	mm
package width	4.9	5	5.1	mm
package height	0.8	0.9	1	mm
nominal pitch	-	0.4	-	mm
actual quantity of termination	-	40	-	



H-PQFN40, thermal enhanced - plastic quad flat non-lead, 40 terminals, 0.4 mm pitch, 5 mm x 5 mm x 0.9 mm body

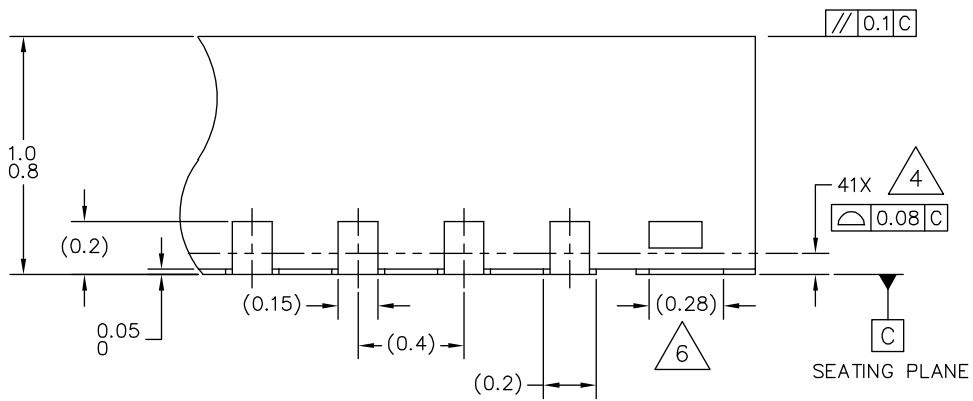
2 Package outline



H-PQFN40, thermal enhanced - plastic quad flat non-lead, 40 terminals, 0.4 mm pitch, 5 mm x 5 mm x 0.9 mm body

H-PQFN-40 I/O
5 X 5 X 0.9 PKG, 0.4 PITCH

SOT2231-1



DETAIL E
VIEW ROTATED 90° CW

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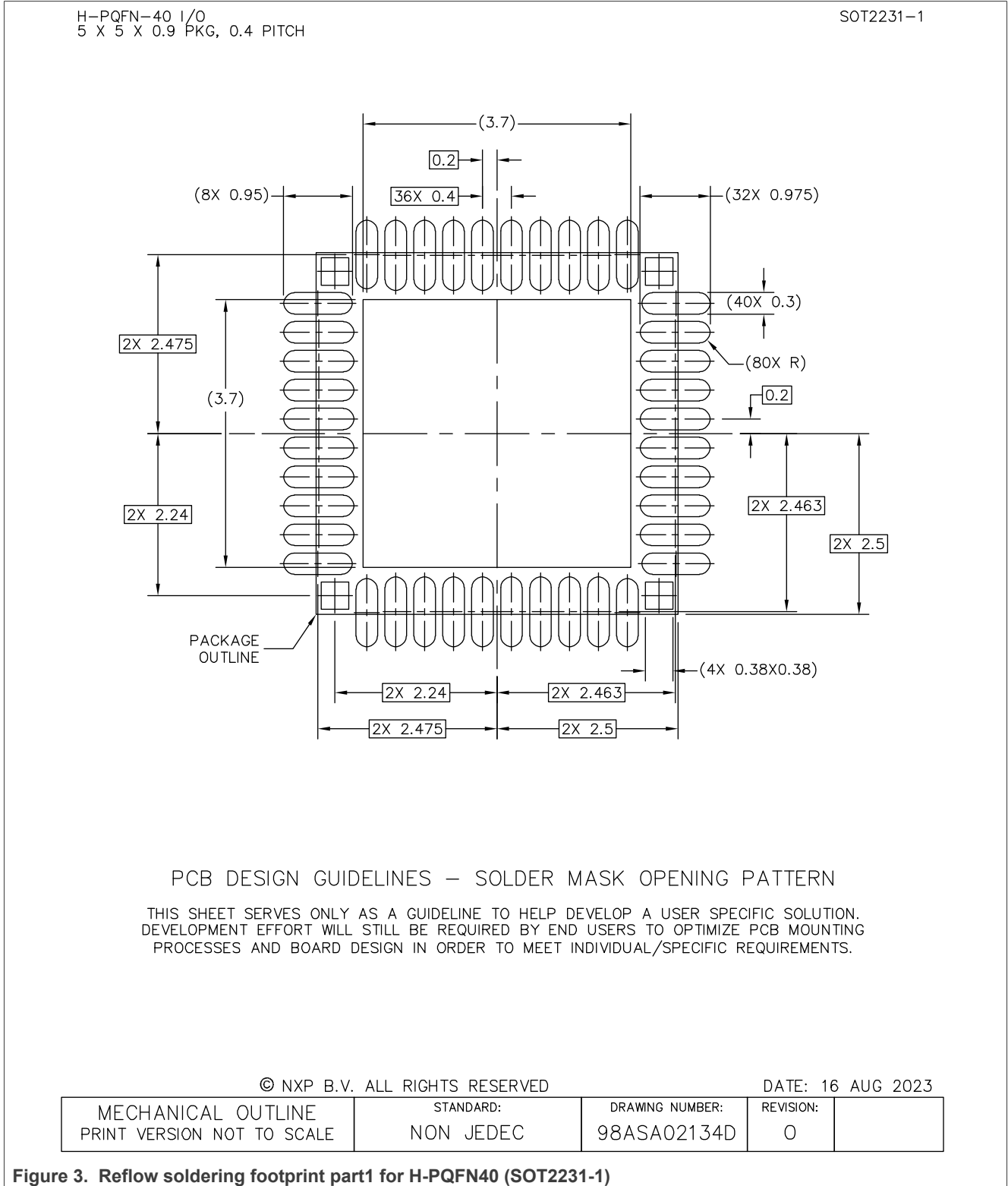
DATE: 16 AUG 2023

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Figure 2. Package outline detail E of H-PQFN40 (SOT2231-1)

H-PQFN40, thermal enhanced - plastic quad flat non-lead, 40 terminals, 0.4 mm pitch, 5 mm x 5 mm x 0.9 mm body

3 Soldering



H-PQFN40, thermal enhanced - plastic quad flat non-lead, 40 terminals, 0.4 mm pitch, 5 mm x 5 mm x 0.9 mm body

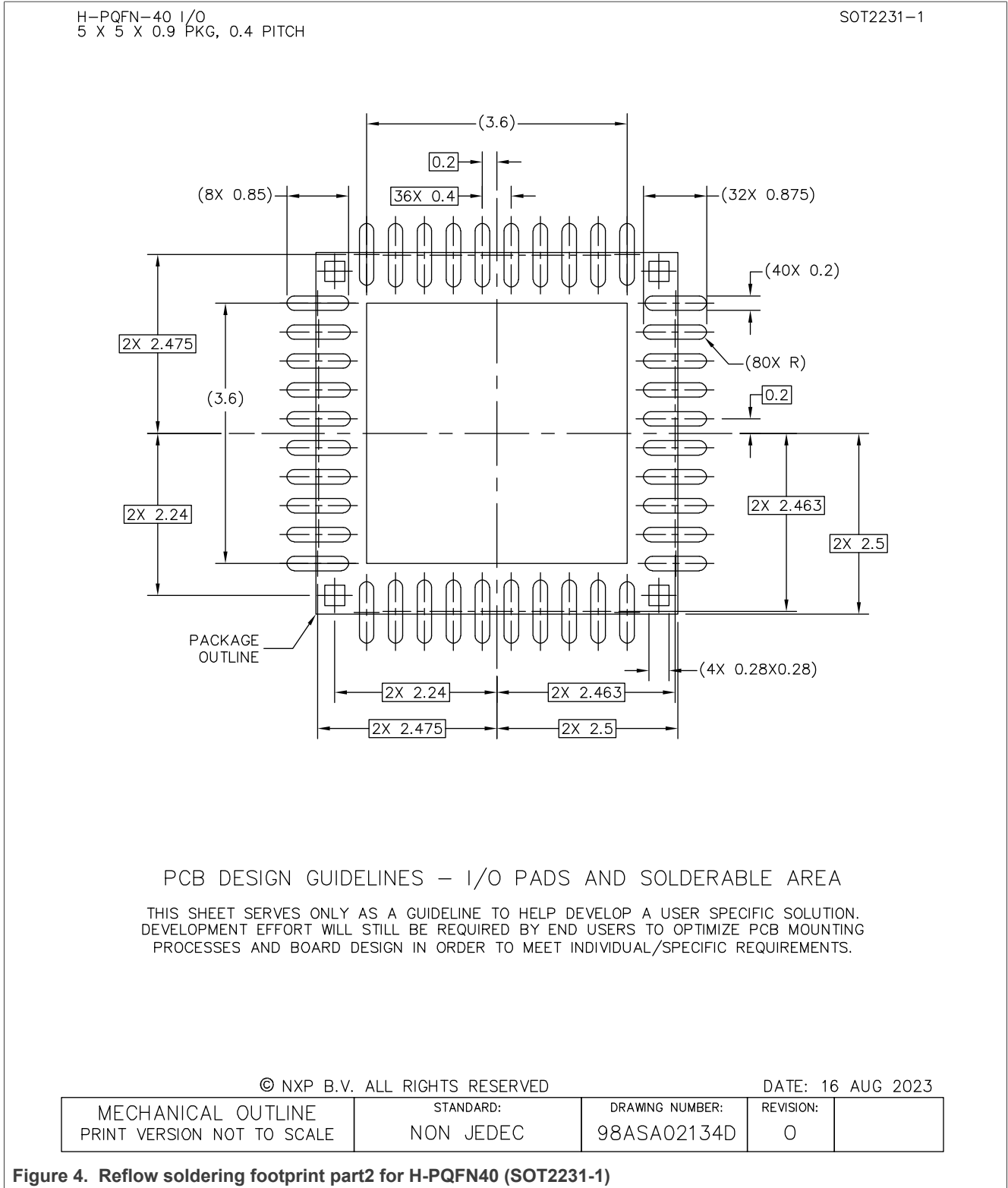


Figure 4. Reflow soldering footprint part2 for H-PQFN40 (SOT2231-1)

H-PQFN40, thermal enhanced - plastic quad flat non-lead, 40 terminals, 0.4 mm pitch, 5 mm x 5 mm x 0.9 mm body

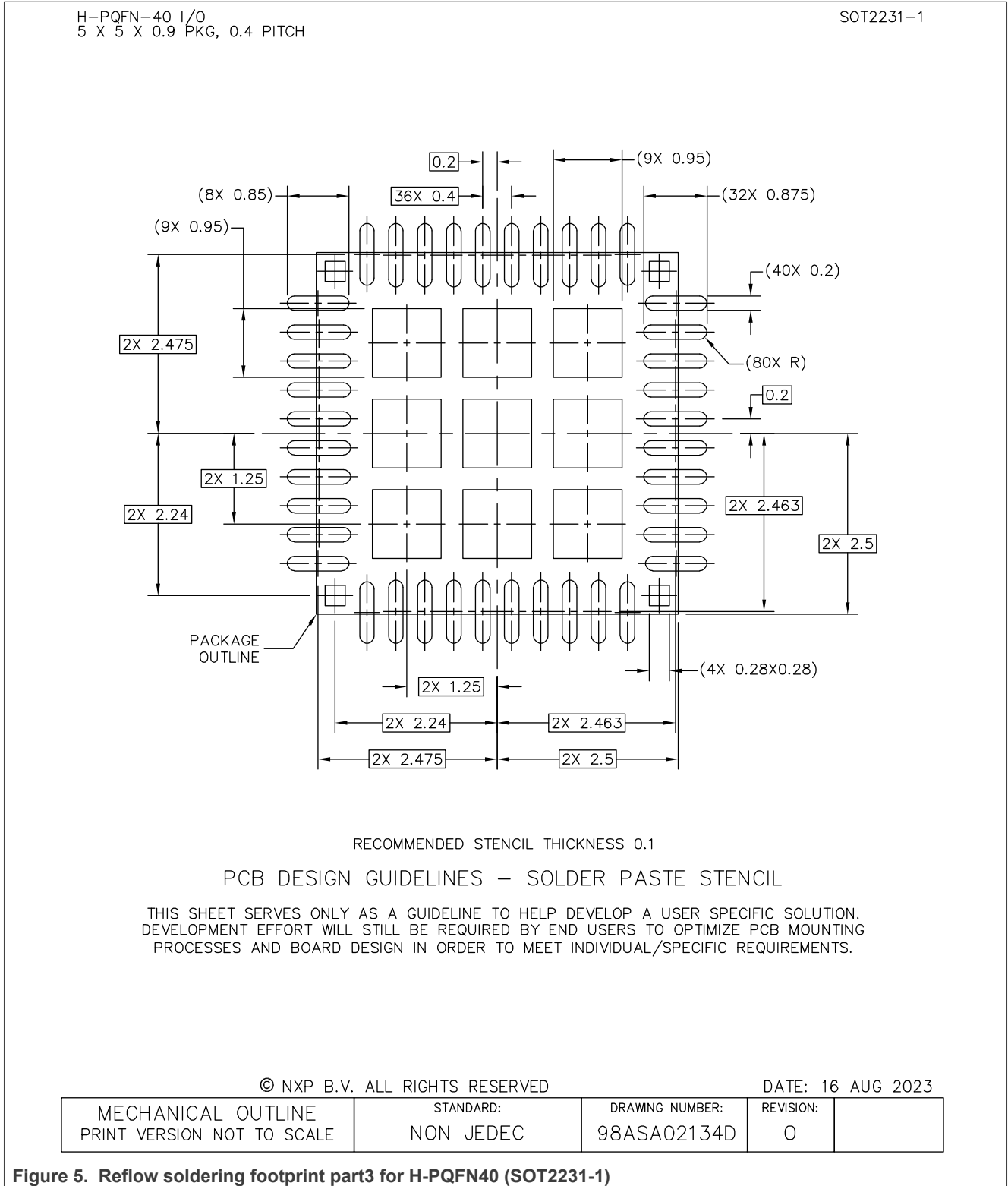


Figure 5. Reflow soldering footprint part3 for H-PQFN40 (SOT2231-1)

H-PQFN40, thermal enhanced - plastic quad flat non-lead, 40 terminals, 0.4 mm pitch, 5 mm x 5 mm x 0.9 mm body

H-PQFN-40 I/O
5 X 5 X 0.9 PKG, 0.4 PITCH

SOT2231-1

NOTES:

1. ALL DIMENSIONS ARE IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3. PIN 1 FEATURE SHAPE, SIZE AND LOCATION MAY VARY.
4. COPLANARITY APPLIES TO LEADS AND DIE ATTACH PAD.
5. MIN. METAL GAP FOR LEAD TO EXPOSED PAD SHALL BE 0.25 MM.
6. ANCHORING PADS.

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Figure 6. Package outline note H-PQFN40 (SOT2231-1)

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H-PQFN40, thermal enhanced - plastic quad flat non-lead, 40 terminals, 0.4 mm pitch, 5 mm x 5 mm
x 0.9 mm body

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